AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application

1. (Original) An IC card comprising:

(a) a wiring substrate having an external connecting terminal and wiring;

(b) a semiconductor chip disposed over the wiring substrate and connected electrically to the external connecting terminal through the wiring; and

(c) a case which covers the wiring substrate and the semiconductor chip in such a manner that the external connecting terminal of the wiring substrate is exposed,

wherein the case has a first end side near which the external connecting terminal is disposed and a second end side positioned on an opposite side to the first end side, and

wherein a planar outline of the wiring substrate is smaller than half of a planar outline of the case, and the wiring substrate is disposed in an area of the case closer to the first end side with respect to a middle position between the first and the second end side.

2. (Original) An IC card according to claim 1, wherein the semiconductor chip is disposed in an area of the case closer to the first end side with respect to the middle position between the first and the second end side.

3. (Original) An IC card according to claim 1, wherein the case comprises a first case and a second case, one of the first and the second case having a projecting portion in an area other than the area where the wiring substrate is disposed, the other case having a recess portion in an area other than the area where the wiring substrate is disposed, the projecting portion being fitted in the recess portion so as to connect the first and the second case with each other.

4. (Original) An IC card according to claim 3, wherein a tip-side inner periphery portion of the recess portion and a tip-side outer periphery portion of the projecting portion are chamfered.

5. (Original) An IC card according to claim 3, wherein the recess portion and the projecting portion have an aligning function for self-alignmentwise aligning planar

positions of the first and the second case when both said cases are superimposed one over the other.

6. (Original) An IC card according to claim 3, wherein the projecting portion formed over the first or the second case has a function for fixing the case formed with the projecting portion to a carrier temporarily.

7. (Original) An IC card according to claim 1, further comprising a movable switch,

wherein the case comprises a first case and a second case, and in the first or the second case, a mechanism for holding the movable switch is provided in an area other than the area where the wiring substrate is disposed.

8. (Original) An IC card according to claim 1, further comprising a movable switch, wherein the case comprises a first case and a second case, and in the first or the second case, a click mechanism for the movable switch is provided in an area other than the area where the wiring substrate is disposed.

9. (Original) An IC card according to claim 1, further comprising a movable switch,

wherein the case comprises a first case and a second case, and means for fixing the first and the second case to a carrier temporarily are provided in areas of the first and the second case other than the area where the wiring substrate is disposed.

10. (Original) An IC card comprising:

(a) a wiring substrate having an external connecting terminal and wiring;

(b) a semiconductor chip disposed over the wiring substrate and connected electrically to the external connecting terminal through the wiring; and

(c) a case which covers the wiring substrate and the semiconductor chip in such a manner that the external connecting terminal of the wiring substrate is exposed,

wherein a planar outline of the wiring substrate is smaller than half of a planar outline of the case, and

wherein the case comprises:

a first end side near which the external connecting terminal is disposed;

a second end side positioned on an opposite side to the first end side;

a first area closer to the first end side with respect to a middle position between the first and the second end side, with the wiring substrate being disposed in the first area; and

an insulating, second area positioned between the first area and the second end side.

11. (Original) An IC card comprising:

(a) a wiring substrate having a plurality of external connecting terminals and wiring;

(b) a semiconductor chip disposed over the wiring substrate and connected electrically to the external connecting terminals through the wiring; and

(c) a case having an opening into which some of the plural external connecting terminals are exposed, the case covering the wiring substrate and the semiconductor chip and further covering some of the other external connecting terminals.

12. (Original) An IC card according to claim 11, wherein the case has a first end side near which the external connecting terminals are disposed and a second end side positioned on an opposite side to the first end side, and

wherein a planar outline of the wiring substrate is smaller than half of a planar outline of the case, and the wiring substrate is disposed in an area of the case closer to the first end side with respect to a middle position between the first and the second end side.

13-20 (Cancelled)